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### 74LVX161284 Low Voltage IEEE 161284 Translating Transceiver

#### **General Description**

The LVX161284 contains eight bidirectional data buffers and eleven control/status buffers to implement a full IEEE 1284 compliant interface. The device supports the IEEE 1284 standard and is intended to be used in an Extended Capabilities Port mode (ECP). The pinout allows for easy connection from the Peripheral (A-side) to the Host (cable side).

Outputs on the cable side can be configured to be either open drain or high drive ( $\pm$  14 mA) and are connected to a separate power supply pin (V $_{\rm CC}$ -cable) to allow these outputs to be driven by a higher supply voltage than the Aside. The pull-up and pull-down series termination resistance of these outputs on the cable side is optimized to drive an external cable. In addition, all inputs (except HLH) and outputs on the cable side contain internal pull-up resistors connected to the V $_{\rm CC}$ -cable supply to provide proper termination and pull-ups for open drain mode.

Outputs on the Peripheral side are standard low-drive CMOS outputs designed to interface with 3V logic. The DIR input controls data flow on the  $A_1-A_8/B_1-B_8$  transceiver pins.

#### **Features**

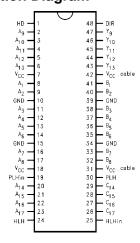
- Supports IEEE 1284 Level 1 and Level 2 signaling standards for bidirectional parallel communications between personal computers and printing peripherals
- Translation capability allows outputs on the cable side to interface with 5V signals
- All inputs have hysteresis to provide noise margin
- B and Y output resistance optimized to drive external cable
- B and Y outputs in high impedance mode during power
- Inputs and outputs on cable side have internal pull-up resistors
- Flow-through pin configuration allows easy interface between the "Peripheral and Host"
- Replaces the function of two (2) 74ACT1284 devices

### **Ordering Code**

Order Number	Package Number	Package Description
74LVX161284MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LVX161284MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

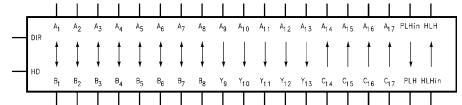
#### **Connection Diagram**



#### **Pin Descriptions**

Pin Names	Description		
HD	High Drive Enable Input (Active HIGH)		
DIR	Direction Control Input		
A <sub>1</sub> -A <sub>8</sub>	Inputs or Outputs		
B <sub>1</sub> –B <sub>8</sub>	Inputs or Outputs		
A <sub>9</sub> -A <sub>13</sub>	Inputs		
Y <sub>9</sub> –Y <sub>13</sub>	Outputs		
A <sub>14</sub> -A <sub>17</sub>	Outputs		
C <sub>14</sub> -C <sub>17</sub>	Inputs		
PLH <sub>IN</sub>	Peripheral Logic HIGH Input		
PLH	Peripheral Logic HIGH Output		
HLH <sub>IN</sub>	Host Logic HIGH Input		
HLH	Host Logic HIGH Output		

## Logic Symbol

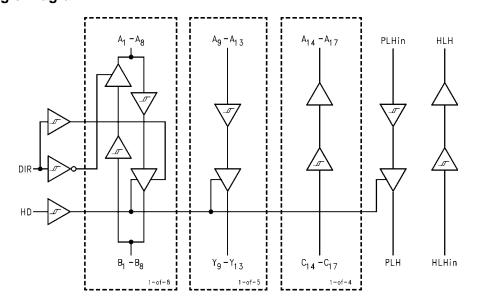


### **Truth Table**

Inputs		Outputs			
DIR	HD				
L	L	B <sub>1</sub> –B <sub>8</sub> Data to A <sub>1</sub> –A <sub>8</sub> , and			
		A <sub>9</sub> -A <sub>13</sub> Data to Y <sub>9</sub> -Y <sub>13</sub> (Note 1)			
		C <sub>14</sub> -C <sub>17</sub> Data to A <sub>14</sub> -A <sub>17</sub>			
		PLH Open Drain Mode			
L	Н	B <sub>1</sub> -B <sub>8</sub> Data to A <sub>1</sub> -A <sub>8</sub> , and			
		A <sub>9</sub> -A <sub>13</sub> Data to Y <sub>9</sub> -Y <sub>13</sub>			
		C <sub>14</sub> -C <sub>17</sub> Data to A <sub>14</sub> -A <sub>17</sub>			
Н	L	A <sub>1</sub> -A <sub>8</sub> Data to B <sub>1</sub> -B <sub>8</sub> (Note 2)			
		A <sub>9</sub> -A <sub>13</sub> Data to Y <sub>9</sub> -Y <sub>13</sub> (Note 1)			
		C <sub>14</sub> -C <sub>17</sub> Data to A <sub>14</sub> -A <sub>17</sub>			
		PLH Open Drain Mode			
Н	Н	A <sub>1</sub> -A <sub>8</sub> Data to B <sub>1</sub> -B <sub>8</sub>			
		A <sub>9</sub> –A <sub>13</sub> Data to Y <sub>9</sub> –Y <sub>13</sub>			
		C <sub>14</sub> –C <sub>17</sub> Data to A <sub>14</sub> –A <sub>17</sub>			

**Note 1:** Y<sub>9</sub>–Y<sub>13</sub> Open Drain Outputs **Note 2:** B<sub>1</sub>–B<sub>8</sub> Open Drain Outputs

### **Logic Diagram**



### Absolute Maximum Ratings(Note 3)

#### **Recommended Operating Conditions**

Supply Voltage

-0.5V to +4.6V  $V_{CC}$ 

-0.5V to +7.0VV<sub>CC—Cable</sub>  $V_{CC\text{—}Cable} \text{ Must Be} \geq V_{CC}$ 

Input Voltage (V<sub>I</sub>)—(Note 4)

 $A_1$ - $A_{13}$ ,  $PLH_{IN}$ , DIR, HD-0.5V to  $V_{CC} + 0.5V$ B<sub>1</sub>-B<sub>8</sub>, C<sub>14</sub>-C<sub>17</sub>, HLH<sub>IN</sub> -0.5V to +5.5V (DC)

B<sub>1</sub>-B<sub>8</sub>, C<sub>14</sub>-C<sub>17</sub>, HLH<sub>IN</sub> -2.0V to +7.0V\* \*40 ns Transient

Output Voltage (V<sub>O</sub>)

-0.5V to  $V_{CC}$  +0.5V  $A_1$ - $A_8$ ,  $A_{14}$ - $A_{17}$ , HLH B<sub>1</sub>-B<sub>8</sub>, Y<sub>9</sub>-Y<sub>13</sub>, PLH -0.5V to +5.5V (DC)  $B_1-B_8$ ,  $Y_9-Y_{13}$ , PLH -2.0V to +7.0V\*

\*40 ns Transient

DC Output Current (I<sub>O</sub>)

 $A_1$ – $A_8$ , HLH ±25 mA  $B_1 - B_8, Y_9 - Y_{13}$  $\pm 50 \text{ mA}$ PLH (Output LOW) 84 mA PLH (Output HIGH) -50 mA

Input Diode Current (I $_{\rm IK}$ )—(Note 4) DIR, HD, A $_9$ -A $_{13}$ , PLH, HLH, C $_{14}$ -C $_{17}$ -20 mA

Output Diode Current (I<sub>OK</sub>)

 $A_1$ - $A_8$ ,  $A_{14}$ - $A_{17}$ , HLH ±50 mA

B<sub>1</sub>-B<sub>8</sub>, Y<sub>9</sub>-Y<sub>13</sub>, PLH -50 mA

DC Continuous  $V_{CC}$  or Ground

Storage Temperature

ESD (HBM) Last Passing Voltage

Supply Voltage

3.0V to 3.6V  $V_{CC}$ 3.0V to 5.5V V<sub>CC—Cable</sub> 0V to V<sub>CC</sub> DC Input Voltage (V<sub>I</sub>)

Open Drain Voltage (V<sub>O</sub>) 0V to 5.5V Operating Temperature (T<sub>A</sub>) -40°C to +85°C

Note 3: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Fairchild does not recom-±200 mA mend operation outside the databook specifications.

-65°C to +150°C Note 4: Either voltage limit or current limit is sufficient to protect inputs.

#### **DC Electrical Characteristics**

	Parameter		v <sub>cc</sub>	V <sub>CC—Cable</sub> (V)	$T_A = 0^{\circ}C$	T <sub>A</sub> = -40°C		
Symbol			(V)		to +70°C	to +85°C	Units	Conditions
			` '	` ,	Guarante	Guaranteed Limits		
V <sub>IK</sub>	Input Clamp		3.0	3.0	-1.2	-1.2	V	I <sub>i</sub> = -18 mA
	Diode Voltage							
V <sub>IH</sub>	Minimum	A <sub>n</sub> , B <sub>n</sub> , PLH <sub>IN</sub> , DIR, HD	3.0-3.6	3.0-5.5	2.0	2.0		
	HIGH Level	C <sub>n</sub>	3.0-3.6	3.0-5.5	2.3	2.3	V	
	Input Voltage	HLH <sub>IN</sub>	3.0-3.6	3.0-5.5	2.6	2.6		
V <sub>IL</sub>	Maximum	A <sub>n</sub> , B <sub>n</sub> , PLH <sub>IN</sub> , DIR, HD	3.0-3.6	3.0-5.5	0.8	0.8		
	LOW Level	C <sub>n</sub>	3.0-3.6	3.0-5.5	0.8	0.8	V	
	Input Voltage	HLH <sub>IN</sub>	3.0-3.6	3.0-5.5	1.6	1.6		
$\Delta V_{T}$	Minimum Input	A <sub>n</sub> , B <sub>n</sub> , PLH <sub>IN</sub> , DIR, HD	3.3	5.0	0.4	0.4		$V_T^+ - V_T^-$
	Hysteresis	C <sub>n</sub>	3.3	5.0	0.8	0.8	V	$V_T^+ - V_T^-$
		HLH <sub>IN</sub>	3.3	5.0	0.2	0.2		$V_T^+ - V_T^-$
V <sub>OH</sub>	Minimum HIGH	A <sub>n</sub> , HLH	3.0	3.0	2.8	2.8		I <sub>OH</sub> = -50 μA
	Level Output		3.0	3.0	2.4	2.4		$I_{OH} = -4 \text{ mA}$
	Voltage	B <sub>n</sub> , Y <sub>n</sub>	3.0	3.0	2.0	2.0	V	I <sub>OH</sub> = -14 mA
		B <sub>n</sub> , Y <sub>n</sub>	3.0	4.5	2.23	2.23	Ī	I <sub>OH</sub> = -14 mA
		PLH	3.15	3.15	3.1	3.1	ĺ	I <sub>OH</sub> = -500 μA

2000V

### DC Electrical Characteristics (Continued)

			T .,	1.,	$T_A = 0^{\circ}C$	$T_A = -40^{\circ}C$			
Symbol	Pa	rameter	V <sub>CC</sub>	V <sub>CC—Cable</sub> (V)	to +70°C	to +85°C	Units	Conditions	
			(V)	(V)	Guaranteed Limits		·		
V <sub>OL</sub>	Maximum LOW	A <sub>n</sub> , HLH	3.0	3.0	0.2	0.2		I <sub>OL</sub> = 50 μA	
	Level Output		3.0	3.0	0.4	0.4		$I_{OL} = 4 \text{ mA}$	
	Voltage	B <sub>n</sub> , Y <sub>n</sub>	3.0	3.0	0.8	0.8	V	I <sub>OL</sub> = 14 mA	
		B <sub>n</sub> , Y <sub>n</sub>	3.0	4.5	0.77	0.77	1 V	I <sub>OL</sub> = 14 mA	
		PLH	3.0	3.0	0.85	0.95		I <sub>OL</sub> = 84 mA	
		PLH	3.0	4.5	0.8	0.9		I <sub>OL</sub> = 84 mA	
R <sub>D</sub>	Maximum Output	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	3.3	3.3	60	60		(NI=1= 5)(NI=1= 7)	
	Impedance		3.3	5.0	55	55		(Note 5)(Note 7)	
	Minimum Output	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	3.3	3.3	30	30	Ω	(NI-1- 5)(NI-1- 7)	
	Impedance		3.3	5.0	35	35		(Note 5)(Note 7)	
R <sub>P</sub>	Maximum Pull-Up	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13,</sub>	3.3	3.3	1650	1650			
	Resistance	C <sub>14</sub> -C <sub>17</sub>	3.3	5.0	1650	1650	Ω		
	Minimum Pull-Up	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	3.3	3.3	1150	1150			
	Resistance	C <sub>14</sub> -C <sub>17</sub>	3.3	5.0	1150	1150	Ω		
I <sub>IH</sub>	Maximum Input	A <sub>9</sub> -A <sub>13</sub> , PLH <sub>IN</sub> ,	3.6	3.6	1.0	1.0		V <sub>I</sub> = 3.6V	
	Current in	HD, DIR, HLH <sub>IN</sub>							
	HIGH State	C <sub>14</sub> -C <sub>17</sub>	3.6	3.6	50.0	50.0	μА	V <sub>I</sub> = 3.6V	
		C <sub>14</sub> -C <sub>17</sub>	3.6	5.5	100	100	-	$V_{I} = 5.5V$	
I <sub>IL</sub>	Maximum Input	A <sub>9</sub> –A <sub>13</sub> , PLH <sub>IN</sub> ,	3.6	3.6	-1.0	-1.0	μА	$V_{I} = 0.0V$	
	Current in	HD, DIR, HLH <sub>IN</sub>							
	LOW State	C <sub>14</sub> -C <sub>17</sub>	3.6	3.6	-3.5	-3.5	mA	$V_{I} = 0.0V$	
		C <sub>14</sub> -C <sub>17</sub>	3.6	5.5	-5.0	-5.0	mA	$V_{I} = 0.0V$	
l <sub>OZH</sub>	Maximum Output	A <sub>1</sub> -A <sub>8</sub>	3.6	3.6	20	20	μА	V <sub>O</sub> = 3.6V	
	Disable Current	B <sub>1</sub> -B <sub>8</sub>	3.6	3.6	50	50	μΑ	V <sub>O</sub> = 3.6V	
	(HIGH)	B <sub>1</sub> -B <sub>8</sub>	3.6	5.5	100	100	μΑ	V <sub>O</sub> = 5.5V	
l <sub>OZL</sub>	Maximum	A <sub>1</sub> -A <sub>8</sub>	3.6	3.6	-20	-20	μА	V <sub>O</sub> = 0.0V	
	Output Disable	B <sub>1</sub> -B <sub>8</sub>	3.6	3.6	-3.5	-3.5	mA		
	Current (LOW)	B <sub>1</sub> -B <sub>8</sub>	3.6	5.5	-5.0	-5.0	mA		
I <sub>OFF</sub>	Power Down	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub> ,							
	Output Leakage	PLH	0.0	0.0	100	100	μА	V <sub>O</sub> = 5.5V	
I <sub>OFF</sub>	Power Down								
011	Input Leakage	C <sub>14</sub> –C <sub>17</sub> , HLH <sub>IN</sub>	0.0	0.0	100	100	μА	$V_I = 5.5V$	
I <sub>OFF</sub> —ICC	Power Down						<b>.</b>		
	Leakage to V <sub>CC</sub>		0.0	0.0	250	250	μА	(Note 6)	
I <sub>OFF</sub> —ICC2	Power Down Leakage								
3 1002	to V <sub>CC—Cable</sub>		0.0	0.0	250	250	μА	(Note 6)	
I <sub>CC</sub>	Maximum Supply		3.6	3.6	45	45	mA	$V_I = V_{CC}$ or GND	
00	Current		3.6	5.5	70	70		$V_I = V_{CC}$ or GND	

Note 5: Output impedance is measured with the output active LOW and active HIGH (HD = HIGH).

Note 6: Power-down leakage to  $V_{CC}$  or  $V_{CC\_Cable}$  is tested by simultaneously forcing all pins on the cable-side (B<sub>1</sub>–B<sub>8</sub>, Y<sub>9</sub>–Y<sub>13</sub>, PLH, C<sub>14</sub>–C<sub>17</sub> and HLH<sub>IN</sub>) to 5.5V and measuring the resulting I<sub>CC</sub> or I<sub>CC\\_Cable</sub>.

Note 7: This parameter is guaranteed but not tested, characterized only.

### **AC Electrical Characteristics**

		T <sub>A</sub> = 0°	C to +70°C	T <sub>A</sub> = -40		Figure Number		
Symbol	Parameter	V <sub>CC</sub> =	3.0V-3.6V	V <sub>CC</sub> =				
		V <sub>CC—Cable</sub>	<sub>e</sub> = 3.0V–5.5V	V <sub>CC—Cabl</sub>	Units			
		Min	Max	Min	Max			
t <sub>PHL</sub>	A <sub>1</sub> -A <sub>8</sub> to B <sub>1</sub> -B <sub>8</sub>	2.0	40.0	2.0	44.0	ns	Figure 1	
t <sub>PLH</sub>	A <sub>1</sub> -A <sub>8</sub> to B <sub>1</sub> -B <sub>8</sub>	2.0	40.0	2.0	44.0	ns	Figure 2	
t <sub>PHL</sub>	B <sub>1</sub> -B <sub>8</sub> to A <sub>1</sub> -A <sub>8</sub>	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>PLH</sub>	B <sub>1</sub> -B <sub>8</sub> to A <sub>1</sub> -A <sub>8</sub>	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>PHL</sub>	A <sub>9</sub> -A <sub>13</sub> to Y <sub>9</sub> -Y <sub>13</sub>	2.0	40.0	2.0	44.0	ns	Figure 1	
t <sub>PLH</sub>	A <sub>9</sub> -A <sub>13</sub> to Y <sub>9</sub> -Y <sub>13</sub>	2.0	40.0	2.0	44.0	ns	Figure 2	
t <sub>PHL</sub>	C <sub>14</sub> -C <sub>17</sub> to A <sub>14</sub> -A <sub>17</sub>	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>PLH</sub>	C <sub>14</sub> -C <sub>17</sub> to A <sub>14</sub> -A <sub>17</sub>	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>SKEW</sub>	LH-LH or HL-HL		10.0		12.0	ns	(Note 9)	
t <sub>PHL</sub>	PLH <sub>IN</sub> to PLH	2.0	40.0	2.0	44.0	ns	Figure 1	
t <sub>PLH</sub>	PLH <sub>IN</sub> to PLH	2.0	40.0	2.0	44.0	ns	Figure 2	
t <sub>PHL</sub>	HLH <sub>IN</sub> to HLH	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>PLH</sub>	HLH <sub>IN</sub> to HLH	2.0	40.0	2.0	44.0	ns	Figure 3	
t <sub>PHZ</sub>	Output Disable Time	2.0	15.0	2.0	18.0		Figure 7	
t <sub>PLZ</sub>	DIR to A <sub>1</sub> -A <sub>8</sub>	2.0	15.0	2.0	18.0	ns		
t <sub>PZH</sub>	Output Enable Time	2.0	50.0	2.0	50.0		Figure 8	
t <sub>PZL</sub>	DIR to A <sub>1</sub> -A <sub>8</sub>	2.0	50.0	2.0	50.0	ns		
t <sub>PHZ</sub>	Output Disable Time	2.0	50.0	2.0	50.0		Figure 9	
t <sub>PLZ</sub>	DIR to B <sub>1</sub> -B <sub>8</sub>	2.0	50.0	2.0	50.0	ns		
t <sub>pEN</sub>	Output Enable Time	2.0	25.0	2.0	28.0		F: 0	
	HD to B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	2.0	25.0	2.0	28.0	ns	Figure 2	
t <sub>pDIS</sub>	Output Disable Time	2.0	25.0	2.0	28.0		Figure 2	
	HD to B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	2.0	25.0	2.0	28.0	ns		
t <sub>pEN</sub> -t <sub>pDIS</sub>	Output Enable-		10.0		12.0	ns		
	Output Disable							
t <sub>SLEW</sub>	Output Slew Rate							
t <sub>PLH</sub>	B <sub>1</sub> -B <sub>8</sub> , Y <sub>9</sub> -Y <sub>13</sub>	0.05	0.40	0.05	0.40	V/ns	Figure 5	
t <sub>PHL</sub>		0.05	0.40	0.05	0.40		Figure 4	
t <sub>r</sub> , t <sub>f</sub>	t <sub>RISE</sub> and t <sub>FALL</sub>		120		120		Figure 6	
	B <sub>1</sub> -B <sub>8</sub> (Note 8),		120		120	ns	(Note 10)	
	Y <sub>9</sub> -Y <sub>13</sub> (Note 8)							

Note 8: Open Drain

Note 9: t<sub>SKEW</sub> is measured for common edge output transitions and compares the measured propagation delay for a given path type:

- (i)  $A_1$ – $A_8$  to  $B_1$ – $B_8$ ,  $A_9$ – $A_{13}$  to  $Y_9$ – $Y_{13}$
- (ii)  $B_1-B_8$  to  $A_1-A_8$
- (iii) C<sub>14</sub>-C<sub>17</sub> to A<sub>14</sub>-A<sub>17</sub>

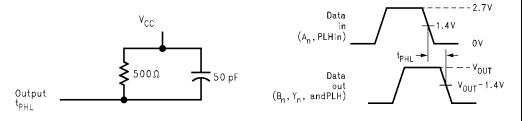
Note 10: This parameter is guaranteed but not tested, characterized only.

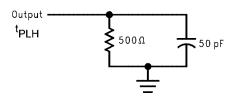
### Capacitance

Symbol	Parameter	Тур	Units	Conditions
C <sub>IN</sub>	Input Capacitance	3	pF	$V_{CC} = 0.0V$ (HD, DIR, $A_9$ - $A_{13}$ , $C_{14}$ - $C_{17}$ , PLH <sub>IN</sub> and HLH <sub>IN</sub> )
C <sub>I/O</sub> (Note 11)	I/O Pin Capacitance	5	pF	V <sub>CC</sub> = 3.3V

Note 11: C<sub>I/O</sub> is measured at frequency = 1 MHz, per MIL-STD-883B, Method 3012

AC Loading and Waveforms Pulse Generator for all pulses: Rate  $\le$  1.0 MHz; Z  $_O \le 50\Omega;$  t  $_f \le$  2.5 ns, t  $_r \le$  2.5 ns.





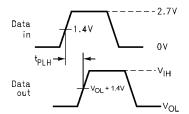


FIGURE 1. Port A to B and A to Y Propagation Delay Waveforms

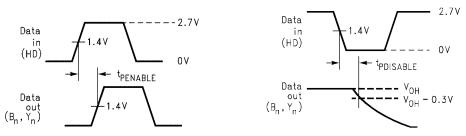


FIGURE 2. Port A to B and A to Y Output Waveforms

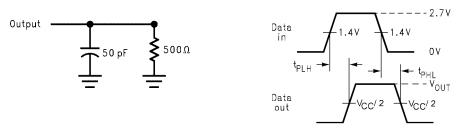
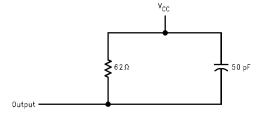


FIGURE 3. Port B to A, C to A and HLHin to HLH Propagation Delay Waveforms

### AC Loading and Waveforms (Continued)



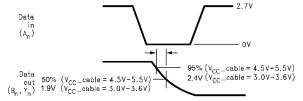


FIGURE 4. Port A to B and A to Y HL Slew Test Load and Waveforms

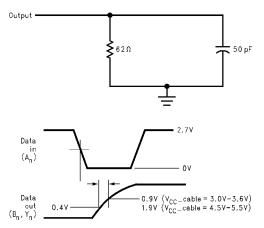
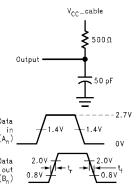


FIGURE 5. Port A to B and A to Y LH Slew Test Load and Waveforms

### AC Loading and Waveforms (Continued)



- $t_{\text{r}} = \text{Output Rise Time, Open Drain}$
- $t_{\rm f}$  = Output Fall Time, Open Drain

#### FIGURE 6. Ports A to B and A to Y Rise and Fall Test Load and Waveforms for Open Drain Outputs

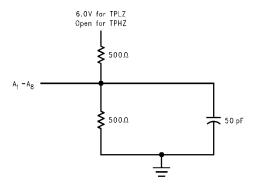
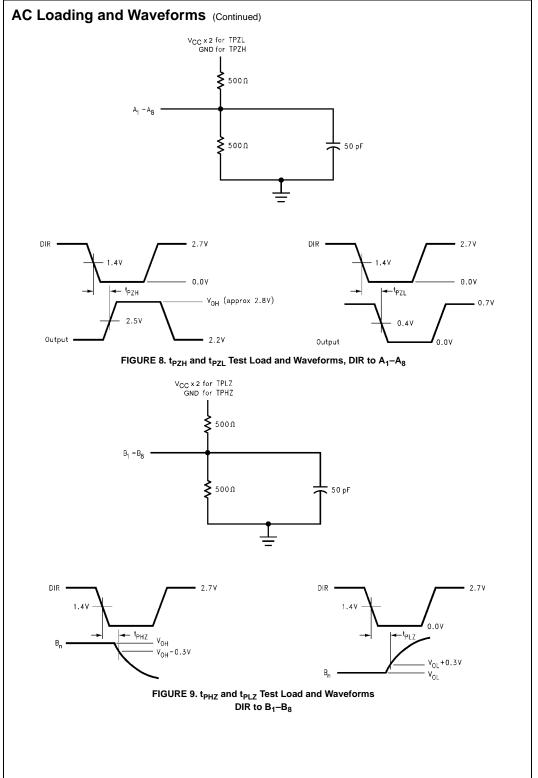
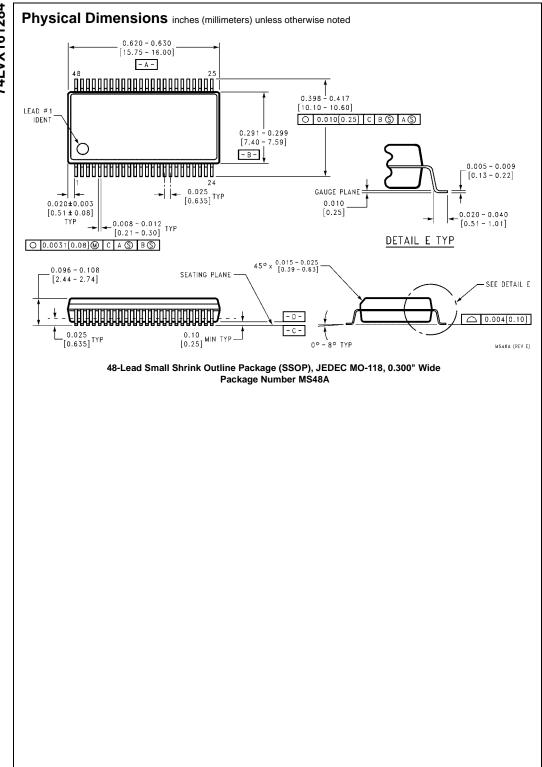




FIGURE 7.  $t_{\mbox{\scriptsize PHZ}}$  and  $t_{\mbox{\scriptsize PLZ}}$  Test Load and Waveforms, DIR to  $\mbox{\scriptsize A}_1\mbox{\scriptsize -A}_8$ 





#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) -12.50±0.10 0.40 TYP -B-0±0.10 99 3.20 8.10 4.05 O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION □ 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20-0.10±0.05 0.50 0.17-0.27 **♦** 0.13**®** A B\$ C\$ 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 - 1.DD C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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